

**F. No. 28(9)/2013-IPHW
GOVERNMENT OF INDIA
MINISTRY OF COMMUNICATIONS & INFORMATION TECHNOLOGY
DEPARTMENT OF ELECTRONICS & INFORMATION TECHNOLOGY
ELECTRONICS NIKETAN, 6, CGO COMPLEX, LODHI ROAD, NEW DELHI -110003**

Dated: 19/3/2014

DeitY invites proposals (Technical & Financial) from eligible bidders which are valid for a minimum period of 90 days from the date of submission (**i.e., till 03/07/2014**) on behalf of the President of India for "**Legal Services for support to DeitY and Government of India to set up Semiconductor Wafer FAB facilities in India**".

Non-Refundable Document Fee	Rs. 5000/- (Rupees five thousand only)
Earnest Money Deposit to be submitted	Rs. 2,00,000/- (Rupees two lakh only)
Last day of submission of pre-bid queries	22.3.2014 (3:00 PM IST)
Date and time of pre-bid meeting	24.3.2014 (2:30 PM IST)
Issue of corrigendum/ clarifications	26.3.2014
Last day of submission	04.04.2014 (3:00 PM)

Prospective bidders desirous of participating in this RFP may submit their queries to the undersigned as per the timelines mentioned above. Based on queries received, if required, DeitY may issue corrigendum/clarifications.

Interested parties may view and download the RFP document containing the detailed terms & conditions, evaluation criteria, and scope of work from the website <https://eprocure.gov.in/eprocure/app> or www.deity.gov.in.

(Note: Go to advanced search option and choose organization name as Department of Electronics and Information Technology and click to submit button).


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